



N-CHANNEL MOSFET

Qualified per MIL-PRF-19500/555

DESCRIPTION

This 2N6790 device is military qualified up to a JANTXV level for high-reliability applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

Important: For the latest information, visit our website http://www.microsemi.com.

• JEDEC registered 2N6790.

- JAN, JANTX, and JANTXV qualifications are available per MIL-PRF-19500/555.
- RoHS compliant versions available (commercial grade only).

APPLICATIONS / BENEFITS

FEATURES

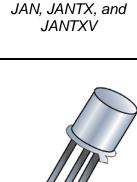
- High frequency operation.
- Lightweight package.
- ESD to class 1A.

MAXIMUM RATINGS @ $T_c = +25$ °C unless otherwise noted

Parameters / Test Conditions	Symbol	Value	Unit
Junction & Storage Temperature	T _J , T _{stg}	-55 to +150	°C
Thermal Resistance Junction-to-Case	R _{ejc}	6.25	°C/W
Drain to Gate Voltage	V _{DG}	200	V
Drain – Source Voltage	V _{DS}	200	V
Gate – Source Voltage	V _{GS}	± 20	V
Continuous Drain Current @ T _C = +25 °C	I _{D1}	3.5	А
Continuous Drain Current @ T _C = +100 °C	I _{D2}	2.25	А
Off-State Power Dissipation (1)	P _{D1}	20	W
Source Current – Drain Diode (Forward Biased V _{SD})	Is	3.5	А
Off-State Current	I _{DM}	14	A (pk)
Drain to Source On State Resistance (2)	r _{DS(on)}	0.80	Ω

<u>Notes</u>: 1. Derated linearly by 0.16 W/°C for $T_c > +25$ °C.

2. V_{GS} = 10 V, I_D = 2.25 A.



Qualified Levels:

TO-205AF (formerly TO-39) Package

Also available in:

U-18 LCC Package (surface mount)

MSC – Lawrence

6 Lake Street, Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

MSC – Ireland

Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298

Website:

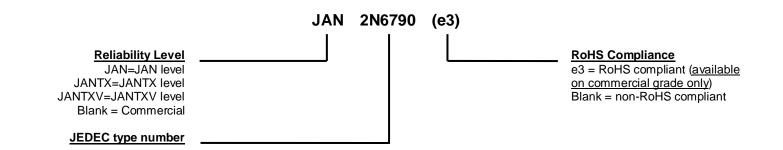
www.microsemi.com



MECHANICAL and PACKAGING

- CASE: Hermetically sealed, kovar base, nickel cap.
- TERMINALS: Tin/lead solder dip nickel plate or RoHS compliant pure tin (commercial grade only) plate.
- MARKING: Part number, date code, manufacturer's ID.
- POLARITY: NPN (see package outline).
- WEIGHT: Approximately 1.064 grams.
- See <u>Package Dimensions</u> on last page.

PART NOMENCLATURE



	SYMBOLS & DEFINITIONS			
Symbol	Definition			
ID	Drain current.			
l _F	Forward current.			
Tc	Case temperature.			
V _{DD}	Drain supply voltage.			
V _{DS}	Drain to source voltage.			
V _{GS}	Gate to source voltage.			



ELECTRICAL CHARACTERISTICS @ T_A = +25 °C, unless otherwise noted

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
OFF CHARACTERTICS			I	
Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	V _{(BR)DSS}	200		V
Gate-Source Voltage (Threshold) $V_{DS} \ge V_{GS}$, $I_D = 0.25 \text{ mA}$ $V_{DS} \ge V_{GS}$, $I_D = 0.25 \text{ mA}$, $T_j = +125 \text{ °C}$ $V_{DS} \ge V_{GS}$, $I_D = 0.25 \text{ mA}$, $T_j = -55 \text{ °C}$	V GS(th)1 V GS(th)2 V GS(th)3	2.0 1.0	4.0 5.0	V
Gate Current $V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}$ $V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0 \text{ V}, \text{ T}_{j} = +125 \text{ °C}$	I _{GSS1} I _{GSS2}		±100 ±200	nA

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
ON CHARACTERTICS	I.			
Drain Current				
$V_{GS} = 0V, V_{DS} = 160 V$	I _{DSS1}		25	μA
$V_{GS} = 0V, V_{DS} = 160 V, T_j = +125 \text{ °C}$	I _{DSS2}		0.25	mA
Static Drain-Source On-State Resistance				
V_{GS} = 10 V, I_D = 2.25 A pulsed	r _{DS(on)1}		0.80	Ω
V_{GS} = 10 V, I_D = 3.5 A pulsed	r _{DS(on)2}		0.85	Ω
T _i = +125 °C:				
V_{GS} = 10 V, I _D = 2.25 A pulsed	r _{DS(on)3}		1.50	Ω
Diode Forward Voltage				
$V_{GS} = 0 \text{ V}, I_D = 3.5 \text{ A pulsed}$	V		1 5	V
V_{GS} = 0 V, I _D = 2.8 A pulsed	V _{SD}		1.5	V

DYNAMIC CHARACTERISTICS

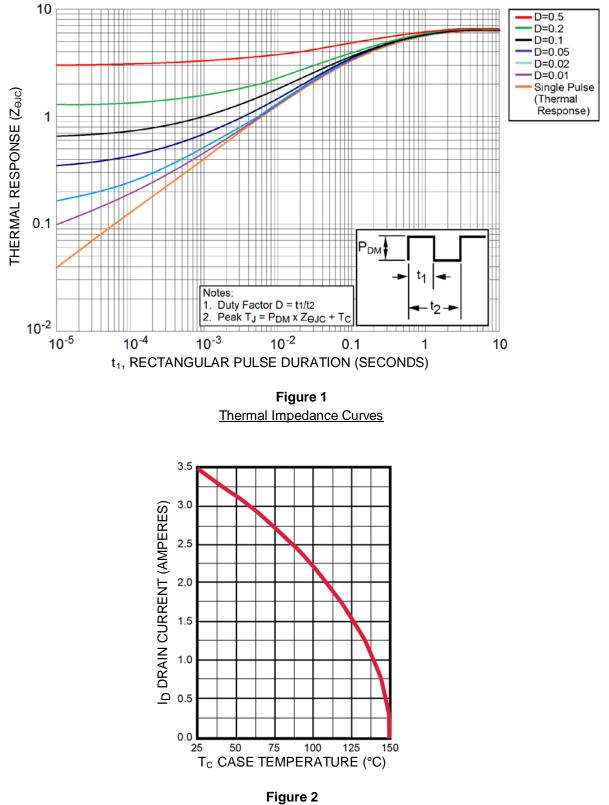
Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Gate Charge:				
On-State Gate Charge	Q _{g(on)}		14.3	
Gate to Source Charge	Q _{gs}		3.0	nC
Gate to Drain Charge	Q _{gd}		9.0	

SWITCHING CHARACTERISTICS

Parameters / Test	Symbol	Min.	Max.	Unit	
Switching time tests: Turn-on delay time Rinse time Turn-off delay time Fall time	I_D = 3.5A, V _{GS} = 10 V Gate drive impedance = 7.5 Ω, V _{DD} = 74 V	t _{d(on)} t _r t _{d(off)} t _f		40 50 50 50	ns
Reverse Recovery Time:	di/dt = 100 A/µs, V _{DD} ≤ 50 V, I _F = 3.5 A	t _{rr}		400	ns



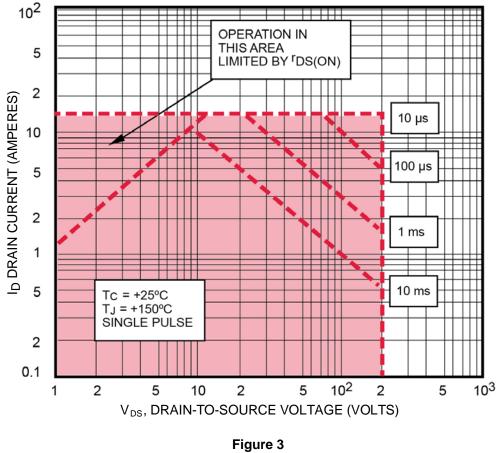
GRAPHS



Maximum Drain Current vs. Case Temperature Graph



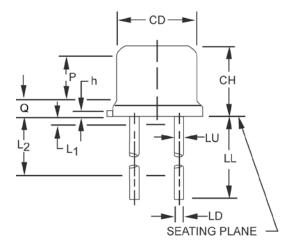
GRAPHS (continued)

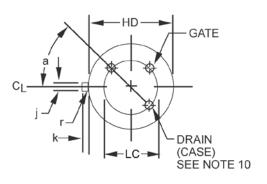


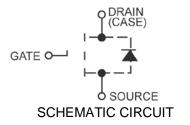
Maximum Safe Operating Area



PACKAGE DIMENSIONS







NOT	ES:	

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. Beyond r (radius) maximum, TL shall be held for a minimum length of .011 inch (0.28 mm).
- 4. Dimension TL measured from maximum HD.
- 5. Body contour optional within zone defined by HD, CD, and Q.
- Leads at gauge plane .054 +.001 -.000 inch (1.37 +0.03 -0.00 mm) below seating plane shall be within .007 inch (0.18 mm) radius of true position (TP) at maximum material condition (MMC) relative to tab at MMC.
- 7. Dimension LU applies between L1 and L2. Dimension LD applies between L2 and LL minimum. Diameter is uncontrolled in L1 and beyond LL minimum.
- 8. All three leads.
- 9. The collector shall be internally connected to the case.
- 10. Dimension r (radius) applies to both inside corners of tab.
- 11. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.
- 12. Lead 1 = source, lead 2 = gate, lead 3 = drain.

	Dimensions				
Ltr	Inch	nes	Millimeters		Notes
	Min	Max	Min	Max	
CD	.305	.335	7.75	8.51	
СН	.160	.180	4.07	4.57	
HD	.335	.370	8.51	9.40	
h	.009	.041	0.23	1.04	
J	.028	.034	0.71	0.86	3
k	.029	.045	0.74	1.14	3, 4
LD	.016	.021	0.41	0.53	7, 8
LL	.500	.750	12.7	19.05	7, 8, 12
LS	.200	TP	5.0	8 TP	6
LU	.016	.019	0.41	0.48	7, 8
L1		.050		1.27	7, 8
L2	.250		6.35		7, 8
Р	.100		2.54		
Q		.050		1.27	5
r		.010		0.25	10
α	45°	TP	45° TP		6